

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L3	224	((test near4 pattern) same configur\$4) and correla\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 12:27
S1	290	(test same pattern same fabricat\$4 same wafer) and configur\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/06 18:12
S2	79	(test same pattern same fabricat\$4 same wafer) and configur\$4 and layout and device	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 07:49
S3	5	(test same pattern same fabricat\$4 same wafer same configur\$4) and layout	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 07:52
S4	50	(pattern same fabricat\$4 same wafer same configur\$4) and correla\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 07:58
S5	2	((test near4 pattern) same fabricat\$4 same configur\$4) and correla\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 07:59
S7	21	((test near4 pattern) same configur\$4) and correla\$4 and fabricat\$4 and layout	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 08:07

	Document ID	Issue Date	Title
1	US 20050081179 A1	20050414	Method and apparatus for generating an OPC segmentation based on modeled intensity gradients
2	US 20050041454 A1	20050224	Failure analysis vehicle for yield enhancement with self test at speed burnin capability for reliability testing
3	US 20040183013 A1	20040923	Electron beam apparatus and method of manufacturing semiconductor device using the apparatus
4	US 20040167764 A1	20040826	METHOD AND SYSTEM FOR GENERATING AN ATPG MODEL OF A MEMORY FROM BEHAVIORAL DESCRIPTIONS
5	US 20030155927 A1	20030821	Multiple directional scans of test structures on semiconductor integrated circuits
6	US 20030096436 A1	20030522	Test structures and methods for inspection of semiconductor integrated circuits
7	US 20020187582 A1	20021212	Inspectable buried test structures and methods for inspecting the same
8	US 20020109090 A1	20020815	Electron beam apparatus and method of manufacturing semiconductor device using the apparatus
9	US 6867606 B2	20050315	Multiple directional scans of test structures on semiconductor integrated circuits
10	US 6842712 B2	20050111	Method for testing an electronic component; computer program product, computer readable medium, and computer embodying the method; and method for downloading the program embodying the method

	Document ID	Issue Date	Title
11	US 6771806 B1	20040803	Multi-pixel methods and apparatus for analysis of defect information from test structures on semiconductor devices
12	US 6636064 B1	20031021	Dual probe test structures for semiconductor integrated circuits
13	US 6633174 B1	20031014	Stepper type test structures and methods for inspection of semiconductor integrated circuits
14	US 6576923 B2	20030610	Inspectable buried test structures and methods for inspecting the same
15	US 6566885 B1	20030520	Multiple directional scans of test structures on semiconductor integrated circuits
16	US 6528818 B1	20030304	Test structures and methods for inspection of semiconductor integrated circuits
17	US 6524873 B1	20030225	Continuous movement scans of test structures on semiconductor integrated circuits
18	US 6509197 B1	20030121	Inspectable buried test structures and methods for inspecting the same
19	US 6445199 B1	20020903	Methods and apparatus for generating spatially resolved voltage contrast maps of semiconductor test structures
20	US 6433561 B1	20020813	Methods and apparatus for optimizing semiconductor inspection tools
21	US 5553249 A	19960903	Dual bus adaptable data path interface system